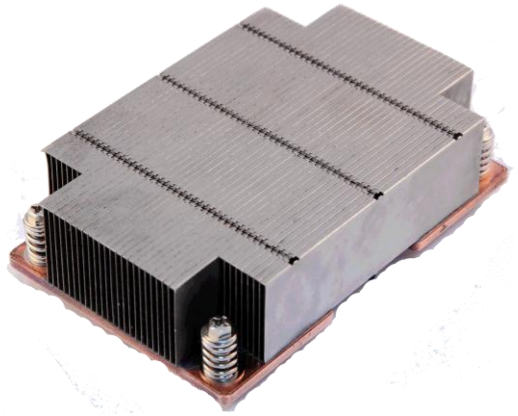
VEL-00010-N1-GP



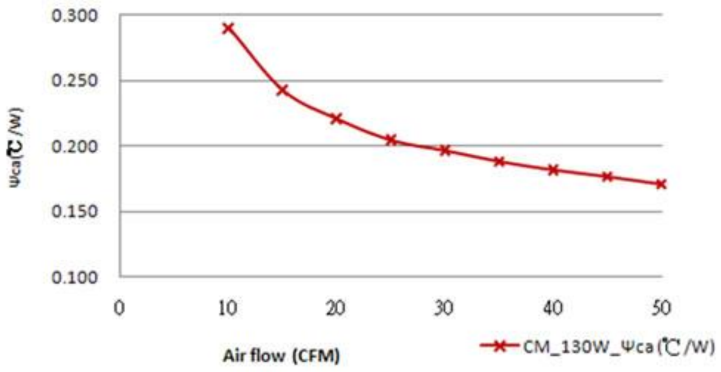
Thermal and Mechanical Spec

Thermal performance for 130W CPU

HSK Assembly Weight: 228 g

CPU Loading: 65 lbf

Performance Curve



Application

LGA 2011 (Socket R Narrow)

Test result:

	130W
Flow (CFM)	Rca (℃/W)
10	0.2904
15	0.2426
20	0.2207
25	0.2045
30	0.1966
35	0.1883
40	0.1818
45	0.1767
50	0.1709

Component Specifications

Application System	1U+ Form Factor Passive Solution
Material	Aluminum Fin + Vapor Chamber Base
Dimension	70L × 107W × 26.5H mm
Fin	Thick=0.3mm, Pitch=1.75mm, 40 fin
Thermal interface Material	Shin Etsu 7783 (40 × 40 mm)

*All readings are typical values at rated voltage.

*Specifications are subjected to change without notice.

Safety